

650V N-Channel Power MOSFET**Features**

- High Voltage: $BV_{DSS}=650V$ (Min.)
- $I_D : 10A$
- Robust high voltage termination
- Avalanche energy specified
- Fast diode recovery time

**TO-262****Pin Definition**

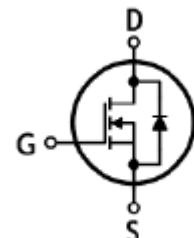
1. Gate
2. Drain
3. Source

Application

- Ballast Bridge
- Switch Mode Power Supplier
- Power Factor Correction
- Lighting

Ordering Information

Type NO	Marking	Package Code
WMC10N65S	10N65C	TO-262

**Absolute maximum ratings ($T_C=25^\circ C$ unless otherwise noted)**

Characteristic	Symbol		Rating	Unit
Drain-source voltage	V_{DSS}		650	V
Gate-source voltage	V_{GSS}		± 20	V
Drain current (DC)	I_D	$T_C=25^\circ C$	10	A
		$T_C=100^\circ C$	6	A
Drain current (Pulsed) ①	I_{DM}		40	A
Single avalanche energy ②	E_{AS}		500	mJ
Power dissipation	P_D		126	W
Junction temperature	T_J		150	$^\circ C$
Storage temperature range	T_{stg}		-55~150	$^\circ C$

* Limited by maximum junction temperature

Characteristic	Symbol		Max	Unit
Thermal resistance	Junction-case	$R_{th(J-C)}$	1.0	$^\circ C/W$
	Junction-ambient	$R_{th(J-A)}$	62.5	

Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Drain-source breakdown voltage	BV_{DSS}	$I_D=250 \mu\text{A}, V_{GS}=0\text{V}$	650	-	-	V
Gate threshold voltage	$V_{GS(\text{th})}$	$I_D=250 \mu\text{A}, V_{DS}=V_{GS}$	2.0	-	4.0	V
Drain-source cut-off current	I_{DSS}	$V_{DS}=600\text{V}, V_{GS}=0\text{V}, T_c=25^\circ\text{C}$	-	-	1	μA
		$V_{DS}=480\text{V}, V_{GS}=0\text{V}, T_c=125^\circ\text{C}$	-	-	10	μA
Gate leakage current	I_{GSS}	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$	-	-	± 0.1	μA
Drain-source on-resistance ⁽³⁾	$R_{DS(\text{on})}$	$V_{GS}=10\text{V}, I_D=5\text{A}$	-	0.75	0.9	Ω
Forward transfer conductance ⁽³⁾	g_{fs}	$V_{DS}=40\text{V}, I_D=5\text{A}$	-	8	-	S
Input capacitance	C_{iss}	$V_{DS}=25\text{V}, V_{GS}=0\text{V}$ $f=1 \text{ MHz}$	-	1840	-	pF
Output capacitance	C_{oss}		-	154	-	
Reverse transfer capacitance	C_{rss}		-	9	-	
Turn-off delay time ⁽³⁾	$t_{d(\text{off})}$	$V_{DD}=300\text{V}, I_D=10\text{A}$ $R_G=25\Omega$	-	130	-	ns
Total gate charge ⁽³⁾	Q_g	$V_{DD}=480\text{V}, V_{GS}=10\text{V}$ $I_D=10\text{A}$	-	45	-	nC
Gate-source charge ⁽³⁾	Q_{gs}		-	7.5	-	
Gate-drain charge ⁽³⁾	Q_{gd}		-	18.5	-	

Source-Drain Diode Ratings and Characteristics ($T_C=25^\circ\text{C}$ unless otherwise noted)

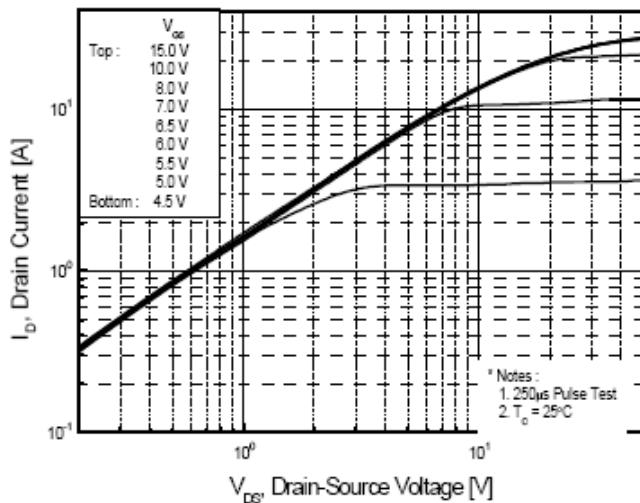
Characteristic	Symbol	Test Condition	Min	Typ	Max	Unit
Source current (DC)	I_S	-	-	-	10	A
Forward voltage ⁽³⁾	V_{SD}	$V_{GS}=0\text{V}, I_{SD}=10\text{A}$	-	-	1.4	V
Reverse recovery time ⁽³⁾	t_{rr}	$I_{SD}=10\text{A}, V_{GS}=0\text{V}$ $dI_F/dt=100\text{A}/\mu\text{s}$	-	420	-	ns
Reverse recovery charge ⁽³⁾	Q_{rr}		-	4.2	-	μC

Note ;

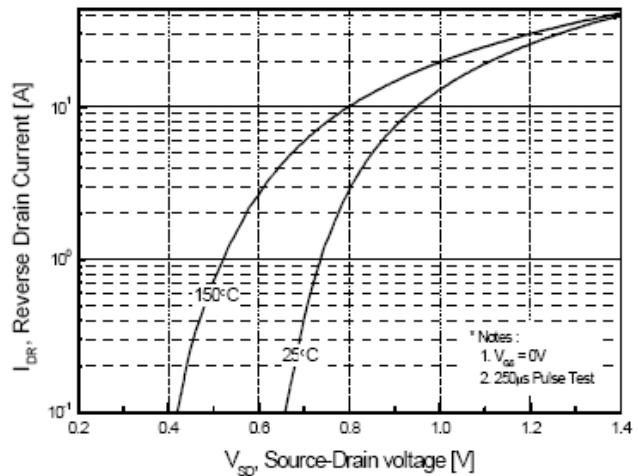
1. Repetitive rating: Pulse width limited by maximum junction temperature
2. Starting $T_j=25^\circ\text{C}$, $V_{DD}=50\text{V}$, $L=10\text{mH}$, $R_G=25\Omega$, $I_{AS}=10\text{A}$
3. Pulse Test : Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$

Electrical Characteristic Curves

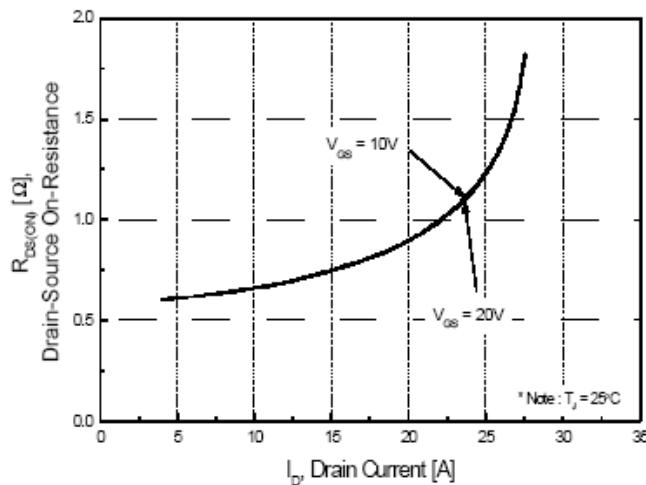
Typical Output Characteristics



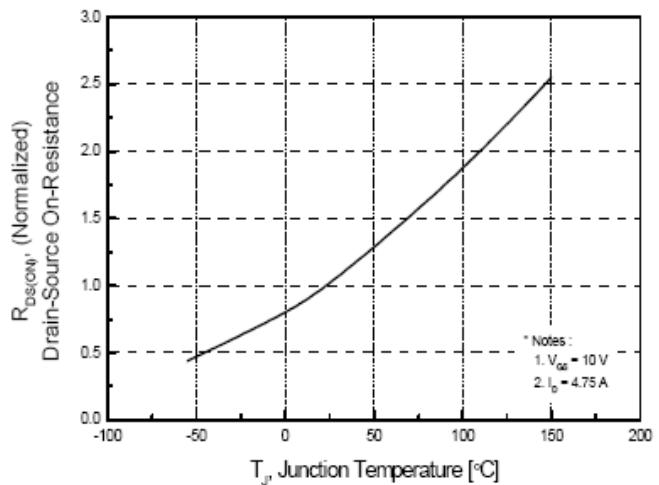
Typical Source-Drain Diode Forward Voltage



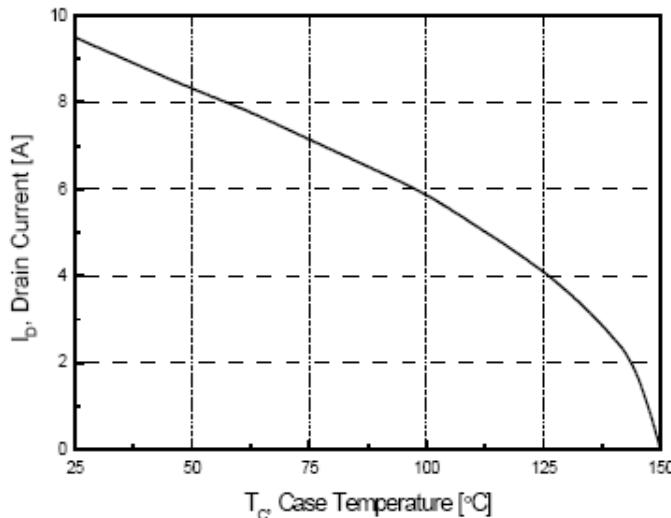
On-Resistance vs. Drain Current and Gate Voltage



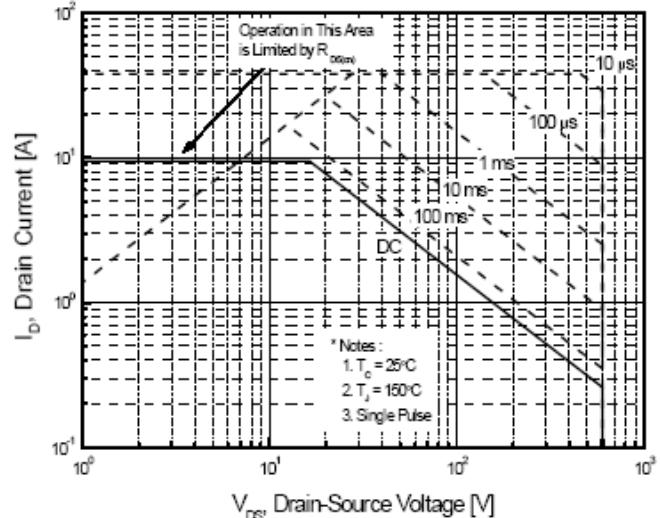
Normalized On-Resistance vs. Junction Temperature



Maximum Drain Current vs. Case Temperature

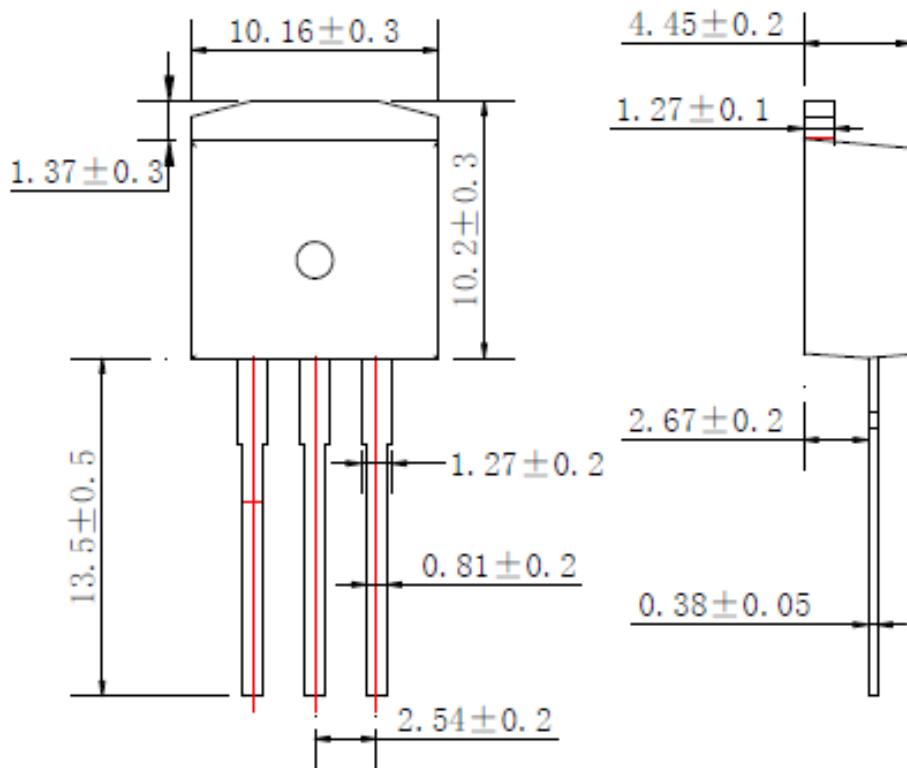
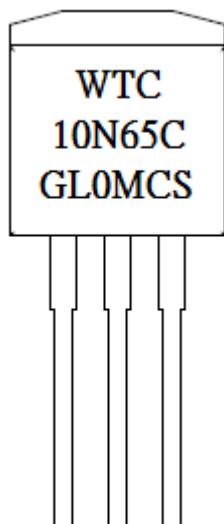


Maximum Safe Operating Area



Outline Dimension : TO-262

Unit : mm

Marking Diagram

First Line	WTC	Company Name	
Second Line	10N65C	Product Code	
Third Line	GL0MCS	1st (Year Code)	A-2010 B-2011 C-2012 ...
		2nd (Month Code)	A-Jan B-Feb C-Mar D-Apr E-May F-Jun G-Jul H-Aug I-Sep J-Oct K-Nov L-Dec
		3rd (Lot Code)	0-1 , A-9
		4th (Product Code)	M-MOS , T-Transistor
		5th (Package Code)	C-TO-262 , I-TO-251 , F-TO220F
		6th (Spec Code)	Assembly Code